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for each of the two relatively large sections, at least one conductive contact pad coupled to at least one of the series of layers of that relatively large section, wherein a predetermined current between at least one conductive contact pad on one of the relatively large sections and at least one conductive pad on the other of the relatively large sections causes the bridge section to initiate a reaction in which the laminate layer is involved.

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7. (Amended) The SCB device of claim 1, wherein the conductive contact pads comprise titanium, nickel and gold.

REMARKS

Entry of this amendment is respectfully requested. No new matter is added by the amendment, because the amended application is fully supported by the application as filed. The amendment to claim 1 makes it clear that there is at least one conductive contact pad associated with each relatively large section of the laminate and that current flow between pads on the two large sections causes the bridge section to initiate the reaction.

Claims 1-28 are in this application; no claims having been cancelled or added; and claims 1 and 7 having been amended by this amendment.

The Restriction Requirement

Applicants elect for examination the claims of Group I, drawn to a semiconductor bridge device. Claims reading on the elected invention are claims 1-7.

Conclusion

Attached hereto is a marked up copy of the changes made to the application by the current amendment. The attached pages are captioned "Amendments to show changes made".

Entry of the amendment is respectfully requested.

Respectfully submitted,

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